# SSM6J08FU

 $\frac{2.1 \pm 0.1}{1.25 \pm 0.1}$ 

0~0.1

: GATE

: SOURCE

0.65

<u>د</u> آي

1, 2, 5, 6 : DRAIN

.0 + 6

3

4

2.0±0.2 1.3±0.1

Power Management Switch DC-DC Converter

• Small Package

TY Semicondutor<sup>®</sup>

• Low on Resistance  $: R_{on} = 0.18 \ \Omega \ (max) \ (@V_{GS} = -4 \ V)$ 

: Ron = 0.26  $\Omega$  (max) (@VGS = -2.5 V)

• Low Gate Threshold Voltage

# Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-Source voltage		V <sub>DS</sub>	-20	V	
Gate-Source voltage		V <sub>GSS</sub>	±12	V	
Drain current	DC	I <sub>D</sub>	-1.3	А	
	Pulse	I <sub>DP</sub> (Note 2)	-2.6	~	
Drain power dissipation		P <sub>D</sub> (Note 1)	300	mW	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	

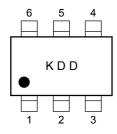
Note1: Mounted on FR4 board (25.4 mm  $\times$  25.4 mm  $\times$  1.6 t, Cu Pad: 0.32 mm  $^2$   $\times$  6) Fig: 1.

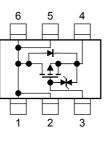
Note2: The pulse width limited by max channel temperature.

# Weight: 6.8 mg (typ.)

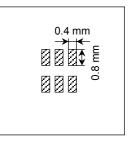
### Marking

### **Equivalent Circuit**





# Fig 1: 25.4 mm $\times$ 25.4 mm $\times$ 1.6 t, Cu Pad: 0.32 mm<sup>2</sup> $\times$ 6



## **Handling Precaution**

When handling individual devices (which are not yet mounted on a circuit board), be sure that the environment is protected against electrostatic electricity. Operators should wear anti-static clothing, and containers and other objects that come into direct contact with devices should be made of anti-static materials.

Unit: mm

0.15±0.05



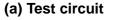
### **Electrical Characteristics (Ta = 25°C)**

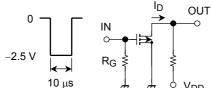
TY Semicondutor<sup>®</sup>

Chara	acteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I <sub>GSS</sub>	$V_{GS} = \pm 12 \text{ V}, \text{ V}_{DS} = 0$	_	_	±1	μA
Drain-Source breakdown voltage	V (BR) DSS	$I_D = -1 \text{ mA}, V_{GS} = 0$	-20	_		v	
	V (BR) DSX	$I_D = -1$ mA, $V_{GS} = 12$ V	-8	_			
Drain Cut-off curre	ent	I <sub>DSS</sub>	$V_{DS} = -20 V, V_{GS} = 0$	_	_	-1	μA
Gate threshold vo	ltage	V <sub>th</sub>	$V_{DS} = -3 V$ , $I_D = -0.1 mA$	-0.5	_	-1.1	V
Forward transfer a	admittance	Y <sub>fs</sub>	$V_{DS} = -3 V$ , $I_D = -0.65 A$ (Note 3)	1.3	2.7		S
Drain-Source ON resistance		R <sub>DS (ON)</sub>	$I_D = -0.65 \text{ A}, V_{GS} = -4 \text{ V}$ (Note 3)	_	140	180	mΩ
			$I_D = -0.65 \text{ A}, V_{GS} = -2.5 \text{ V}$ (Note 3)	_	200	260	
			$I_D = -0.65 \text{ A}, V_{GS} = -2.0 \text{ V}$ (Note 3)	_	260	460	
Input capacitance		C <sub>iss</sub>	$V_{DS} = -10 \text{ V}, \text{ V}_{GS} = 0, \text{ f} = 1 \text{ MHz}$		370		pF
Reverse transfer capacitance		C <sub>rss</sub>	$V_{DS} = -10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$	_	73		pF
Output capacitance		C <sub>oss</sub>	$V_{DS} = -10 \text{ V}, \text{ V}_{GS} = 0, \text{ f} = 1 \text{ MHz}$		116		pF
Switching time	Turn-on time	t <sub>on</sub>	$V_{DD} = -10 \text{ V}, \text{ I}_{D} = -0.65 \text{ A},$	_	33		ns
	Turn-off time	t <sub>off</sub>	$V_{GS} = 0$ ~-2.5 V, $R_G = 4.7 \Omega$		47		ns

Note 3: Pulse test

# **Switching Time Test Circuit**

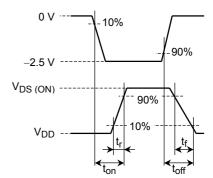




$$\begin{split} V_{DD} &= -10 \ V \\ R_G &= 4.7 \ \Omega \\ D.U. &\leq 1\% \\ V_{IN} : t_r, t_f < 5 \ ns \\ COMMON \ SOURCE \\ Ta &= 25^\circ C \end{split}$$

(b) V<sub>IN</sub>

(c) Vout



#### Precaution

 $V_{th}$  can be expressed as voltage between gate and source when low operating current value is  $I_D$  =  $-100~\mu A$  for this product. For normal switching operation,  $V_{GS}$  (on) requires higher voltage than  $V_{th}$  and  $V_{GS}$  (off) requires lower voltage than  $V_{th}$ .

(relationship can be established as follows:  $V_{GS}$  (off) <  $V_{th}$  <  $V_{GS}$  (on))

Please take this into consideration for using the device.

 $V_{GS}$  recommended voltage of -2.5~V or higher to turn on this product.